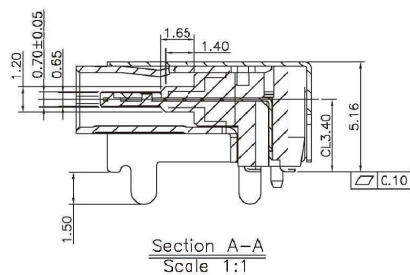
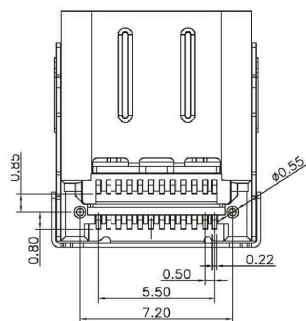
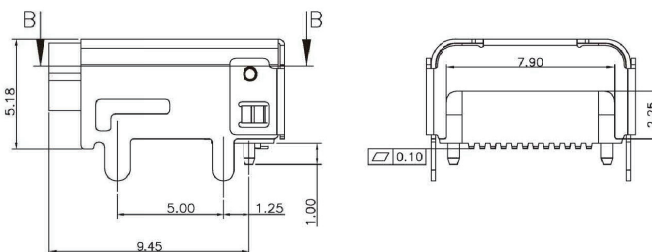
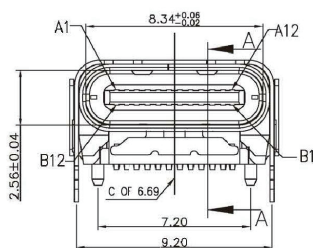
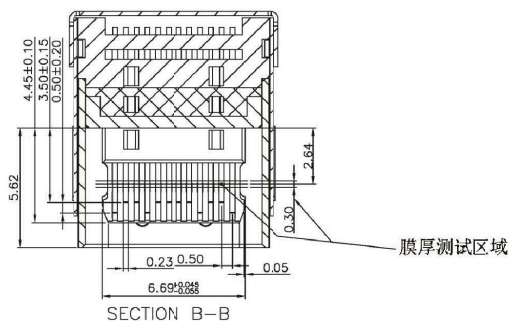
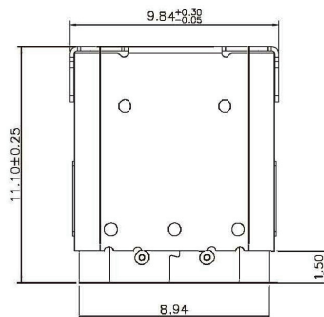


RoHS2.0+REACH



NOTES:

1.MATERIAL:

MOLDING: LCP UL94 V-0

CONTACT: COPPER ALLOY,

PLATED GOLD ON CONTACT AREA,
G/F GOLD ON SOLDER AREA,
50u" NICKEL PLATING OVER ALL.

OUTER SHELL: SUS304, T=0.20±0.03mm

50u" NICKEL PLATING OVER ALL.

G/F FOOT BRUSHING GOLD

INNER SHELL: SUS304, T=0.30±0.03mm

50u" NICKEL PLATING OVER ALL.

LATCH: SUS301, T=0.15±0.03mm

2.MECHANICAL:

INSERTION: 5~20N.

EXTRACTION: 8~20N.

DURABILITY: 10000 CYCLES

3.ELECTRICAL:

CURRENT: 5A MAX FOR VBUS;

1.25A FOR GND, 0.25A FOR OTHER OTHER.

VOLTAGE: 20VDC MAX

WITHSTANDING VOLTAGE: 100V AC.

CONTACT RESISTANCE: 40mΩ MAX.

INSULATION RESISTANCE: 1COMΩ MIN.

4.ENVIRONMENTAL

TEMPERATURE RANGE -40°C ~ +85°C

DRAWING:

Frank

CHECKED:

yangjie

APPROVAL:

GENERAL TOLERANCE

.X:=±0.30

.X*:=±2°

.XX:=±0.25

.XX*:=±1°

.XXX:=±0.15

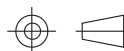
.XXX*:=±0.5°

UNIT: MM

PROJECTION:

SCALE: 1:1

SHEET: 1/1



CHIN-BAN
Electronic Technology

DESCRIPTION: 板上双贴 CL3.40 PH5.0 外壳脚长1.50

PART NO: **USB30-AF-029**

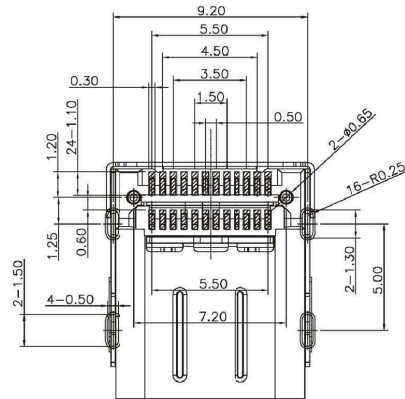
REV: 1.0

OLD CODE: USBC1-AF-029

DRAWING NO:

SIZE: A4

RoHS2.0+REACH



RECOMMENDED PCB LAYOUT(COMPONENT SIDE)

PCB THICKNESS: 1.60±0.05
DEFAULT TOLERANCE: ±0.05

USB TYPE-C FULL-FEATURED RECEPTACLE INTERFACE PIN ASSIGNMENTS

PIN	Signal Name	Description	PIN	Signal Name	Description
A1	GND	Ground return	B12	GND	Ground return
A2	SSTxp1	Positive half of first SuperSpeed TX differential pair	B11	SSRXp1	Positive half of first SuperSpeed RX differential pair
A3	SSTxn1	Negative half of first SuperSpeed TX differential pair	B10	SSRXn1	Negative half of first SuperSpeed RX differential pair
A4	Vbus	Bus Power	B9	Vbus	Bus Power
A5	CC1	Configuration Channel	B8	SBU2	Sideband Use(SBU)
A6	Dp1	Positive half of the USB 2.0 differential pair-Position 1	B7	Dn2	Negative half of the USB 2.0 differential pair-Position 2
A7	Dn1	Negative half of the USB 2.0 differential pair-Position 1	B6	Dp2	Positive half of the USB 2.0 differential pair-Position 2
A8	SBU1	Sideband Use(SBU)	B5	CC2	Configuration Channel
A9	Vbus	Bus Power	B4	Vbus	Bus Power
A10	SSRXn2	Negative half of second SuperSpeed RX differential pair	B3	SSTXn2	Negative half of second SuperSpeed TX differential pair
A11	SSRXp2	Positive half of second SuperSpeed RX differential pair	B2	SSTXp2	Positive half of second SuperSpeed TX differential pair
A12	GND	Ground return	B1	GND	Ground return

8	UPPER CONTACT	12	COPPER ALLOY	PLATED GOLD ON CONTACT AREA, G/F GOLD ON SOLDER AREA, 50u" NICKEL PLATING OVER ALL.
7	LOWER CONTACT	12		
6	LOWER IM	1	THERMOPLASTIC UL 94V-0	COLOR: BLACK
5	UPPER IM	1	THERMOPLASTIC UL 94V-0	COLOR: BLACK
4	OVERMOLD	1	THERMOPLASTIC UL 94V-0	COLOR: BLACK
3	SHIELD PLATE	1	STAINLESS STEEL	CLEAN
2	INNER SHELL	1	STAINLESS STEEL	NICKEL PLATING OVER ALL.
1	OUTER SHELL	1	STAINLESS STEEL	NICKEL PLATING OVER ALL , AU AT SOLDER TAIL
NO.	DESCRIPTION	QTY	MATERIAL	SPECIFICATION

5.0				DRAWING:	GENERAL TOLERANCE	CHIN-BAN Electronic Technology	
4.0				Frank	.X:=±0.30 .X*:=±2° .XX:=±0.25 .XX*:=±1° .XXX:=±0.15 .XXX*:=±0.5°		
3.0				CHECKED:	UNIT: MM PROJECTION:	DESCRIPTION: 板上双贴 CL3.40 PH5.0 外壳脚长1.50	
2.0				yangjie	SCALE: 1:1		
1.0				APPROVAL:	SHEET: 1/1	PART NO: USB30-AF-029	REV: 1.0
NO.	DATE	DESCRIPTION	DRAWING			OLD CODE: USBC1-AF-029	SIZE: A4